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(54) **LAYERED BONDING MATERIAL,
SEMICONDUCTOR PACKAGE, AND POWER
MODULE**

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ABSTRACT

A layered bonding material **10** includes a base material **11**, a first solder section **12a** stacked on a first surface of the base material **11**, and a second solder section **12b** stacked on a second surface of the base material **11**. A coefficient of linear expansion of the base material **11** is 5.5 to 15.5 ppm/K, the first solder section **12a** and the second solder section **12b** are made of lead-free solder, and both of a thickness of the first solder section **12a** and a thickness of the second solder section **12b** are 0.05 to 1.0 mm.

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